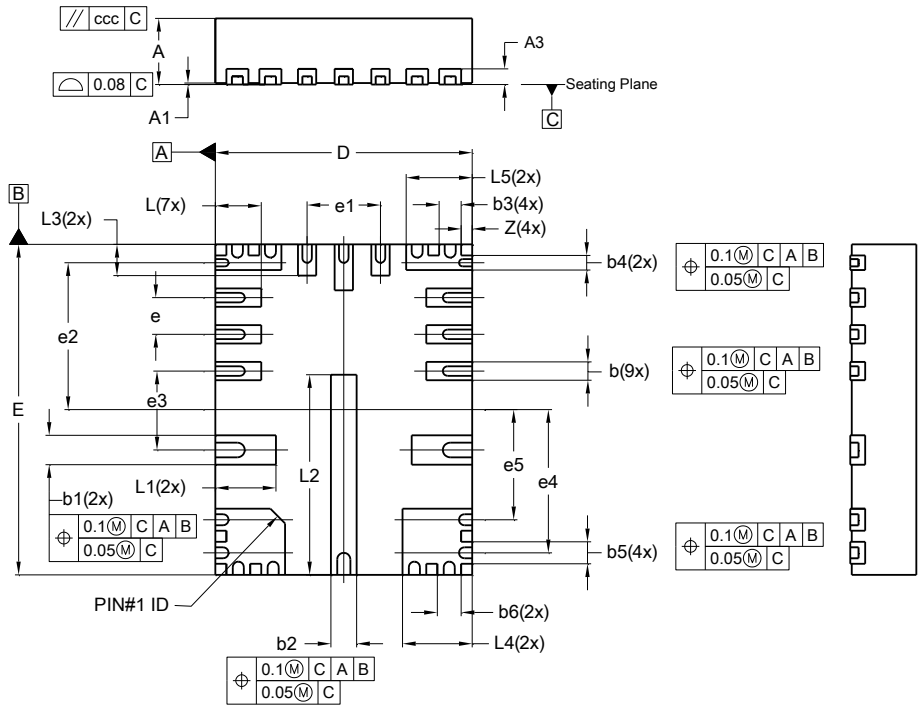
Package Outline Dimensions

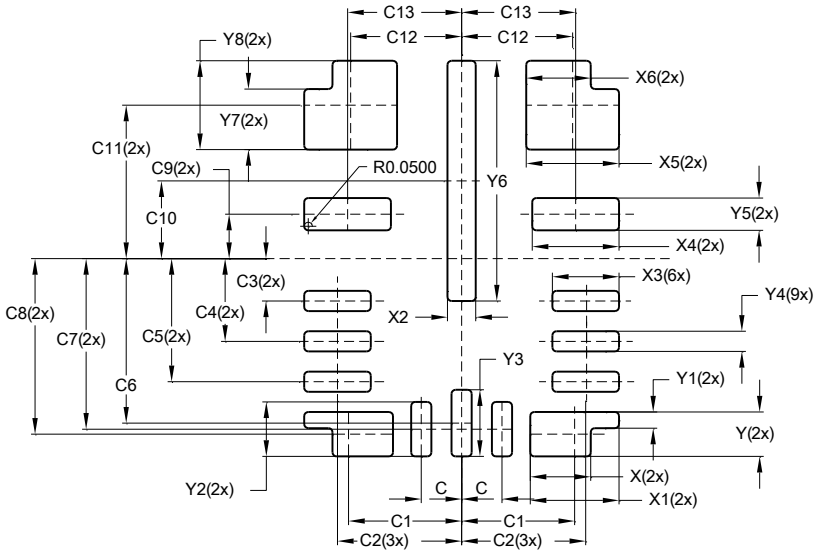
V-QFN3545-16/SWP



V-QFN3545-16/SWP			
Dim	**Min**	**Max**	**Typ**
A	0.80	1.00	0.90
A1	0.00	0.05	0.02
A3	--	--	0.203
b	0.20	0.30	0.25
b1	0.35	0.45	0.40
b2	0.30	0.40	0.35
b3	0.30REF		
b4	0.15	0.25	0.20
b5	0.25	0.35	0.30
b6	0.325REF		
D	3.40	3.60	3.50
E	4.40	4.60	4.50
e	0.50 BSC		
e1	1.00 BSC		
e2	2.00 BSC		
e3	1.075 BSC		
e4	1.95 BSC		
e5	1.50 BSC		
L	0.525	0.725	0.625
L1	0.725	0.925	0.825
L2	2.625	2.825	2.725
L3	0.325	0.525	0.425
L4	0.85	1.05	0.95
L5	0.80	1.00	0.90
z	--	--	0.15
All Dimensions in mm			

Suggested Pad Layout

V-QFN3545-16/SWP



Dim	Value (in mm)	Dim	Value (in mm)
C	0.500	**X1**	1.100
C1	1.400	**X2**	0.350
C2	1.538	**X3**	0.825
C3	0.525	**X4**	1.075
C4	1.025	**X5**	1.150
C5	1.525	**X6**	0.800
C6	2.038	**Y**	0.550
C7	2.113	**Y1**	0.200
C8	2.175	**Y2**	0.675
C9	0.550	**Y3**	0.825
C10	0.963	**Y4**	0.250
C11	1.900	**Y5**	0.400
C12	1.375	**Y6**	2.975
C13	1.413	**Y7**	0.750
X	0.750	**Y8**	1.100

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.